<	SPECIFI	CATION	>
		SPE Date	C.No. ASDIQ-SPE-149(00) e: Aug. 20, 2022
То :			
	CUSTOMER'S PRO	DUCT NAME	
	ASDI PRODUCT NA		
RECEIPT CONFIRMATION	ONSENT	CONDI	TIONAL CONSENT
APPR	OVED	CHE	CKED
ASDI SIGNATURE	01150:755		
APPROVED Xianglong Li	CHECKED Liang Wang	PREPARED Jiayin Cai	



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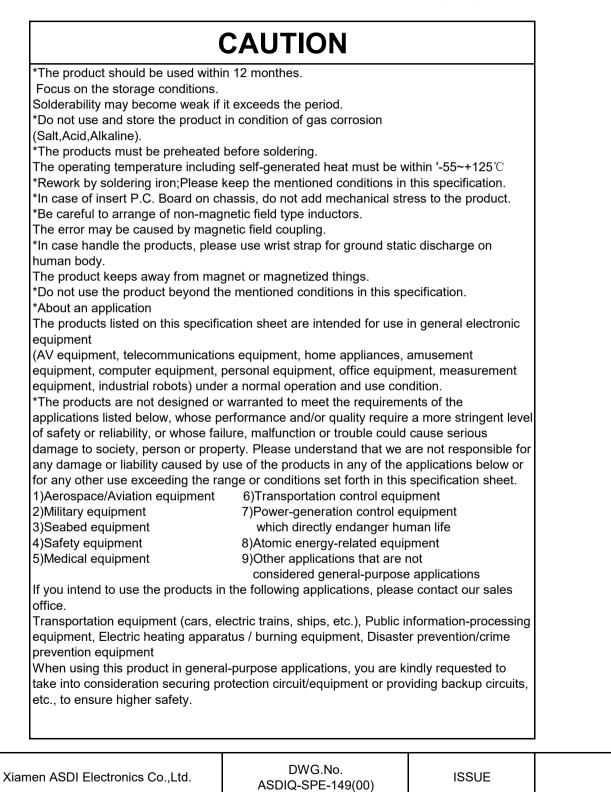
REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	Aug. 20, 2022	New release	Xianglong Li	Liang Wang	Jiayin Cai

# **CAUTION WHEN HANDLING**

Before use the products, please read this specification.

## **CAUTION FOR SAFETY USING**

When use the products, be careful to mentioned below for safety using.



CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
	SIPM0502A-SERIES	

## 1.Applications

Note PC power system, incl. IMVP-6, Switch and servers,Base stations Battery powered devices,SSD modules,DC/DC converter .

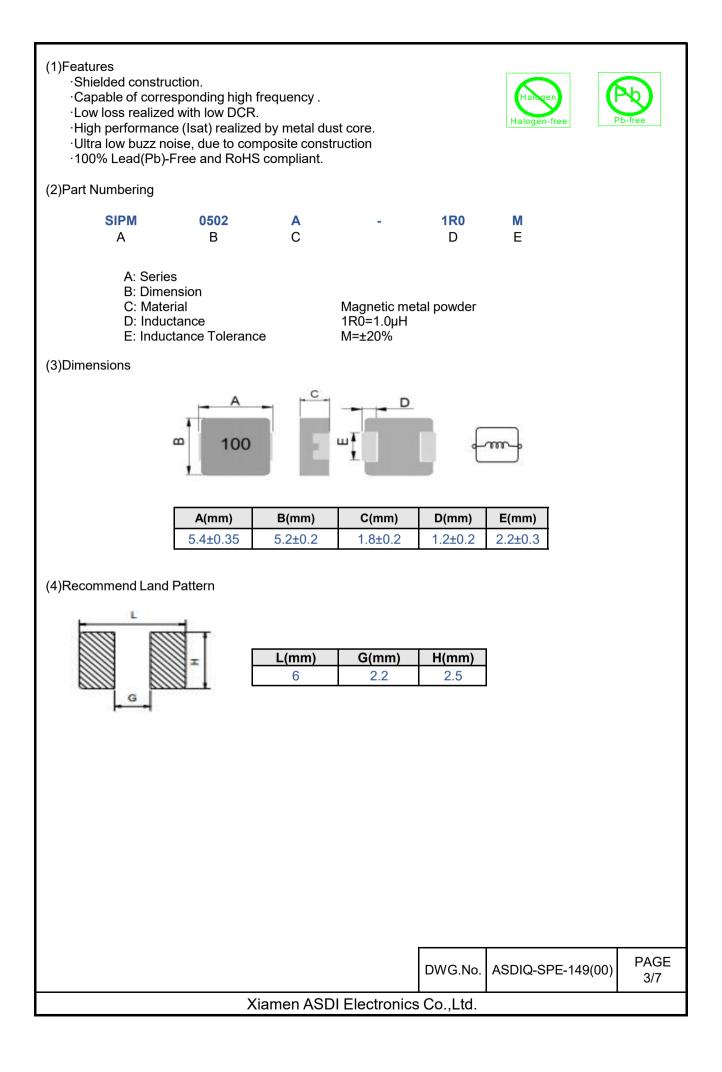
## 2.INDEX

Listed item	Attachment&Tables	Page
1.Features	Please see (1)	3/7
2.Part Numbering	Please see (2)	3/7
3.Dimensions	Please see (3)	3/7
4.Recommend Land Pattern	Please see (4)	3/7
5.Electrical Specifications	Please see (5)	4/7
6.Material List	Please see (6)	5/7
7.Reliability Tests	Please see (7)	5/7
8.Soldering and Mounting	Please see (8)	6/7
9.Packaging Information	Please see (9)	7/7
10.Note	Please see (10)	7/7

## 3.Manufacturing Location

China

	<b></b>		
	DWG.No.	ASDIQ-SPE-149(00)	PAGE 2/8
Xiamen ASDI Electronics	Co.,Ltd.		



## (5)Electrical Specifications

Íable 1

ASDI Part Number		l sat (A)	l rms (A)	DCR (mΩ)
ASDI Part Number	L0(µH) ±20% @ 0 A	Тур.	TYP.	<b>Max.@25</b> ℃
SIPM0502A-R22M	0.22	19.0	15.0	4.50
SIPM0502A-R47M	0.47	16.0	10.5	9.00
SIPM0502A-R56M	0.56	15.0	9.5	10.0
SIPM0502A-1R0M	1.00	9.50	8.0	17.0
SIPM0502A-1R5M	1.50	8.50	5.5	30.0
SIPM0502A-2R2M	2.20	7.00	5.0	34.0
SIPM0502A-3R3M	3.30	5.50	4.5	58.0
SIPM0502A-4R7M	4.70	4.50	3.5	78.0
SIPM0502A-6R8M	6.80	3.50	2.8	120.0
SIPM0502A-8R2M	8.20	3.30	2.6	150.0
SIPM0502A-100M	10.00	3.00	2.5	175.0

#### Note:

1. Test frequency : L : 100KHz /1.0V;

- 2. All test data referenced to  $25\,^\circ\!\mathrm{C}$  ambient.
- 3. Testing Instrument : L/Q: HP4284A,CH11025,CH3302,CH1320 ,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
- 4. Heat Rated Current (Irms) will cause the coil temperature rise approximately  $\Delta$  t of 40 °C (keep 1min.).
- 5. Saturation Current (Isat) will cause L0 to drop 30% typical. (keep quickly).
- 6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Pa

	DWG.No.	ASDIQ-SPE-149(00)	PAGE 4/7
Xiamen ASDI Ele	ectronics Co.,Ltd.		

#### (6)Material List

Symbol	Components	Material
1	Core	Alloy Powder
2	Wire	Polyester Wire or equivalent
3	Solder Plating	100% Pb free solder
4	paint	Epoxy resin
5	Ink	Halogen-free ketone



#### (7)Reliability Tests

No.	Test item	Performance	٦	Fest details
1	Operating temperature	-55~+125°C		
2	Storage temperature and Humidity range	-55∼+125℃,50~60%RH (Product without taping)		
		Electrical Performance Test		
3	Inductance	Defecto standard alectrical alectrostariatica list	HP4284A,CH CH1320S LCI	11025,CH3302,CH1320 R Meter.
4	DCR	Refer to standard electrical characteristics list.	CH16502,Agil Micro-Ohm M	
5	Saturation Current (Isat)	riangle L20% typical.		C Current (Isat) to drop
6	Heat Rated Current (Irms)	Approximately	Heat Rated C the coil tempe rise $\triangle T(^{\circ}C) =$ 1.Applied the current(keep	urrent (Irms) will cause erature without core loss. allowed DC 1 min.). e measured by digital
		Reliability Test		
7	High Temperature Exposure Test		Temperature: Duration:1000 Measured at r placing for 2 t (MIL-PRF-27)	)±12hrs. room temperature after o 3hrs.
8	Biased Humidity Test		Humidity:85±3 Temperature: Duration:1000 Measured at r placing for 2 t (AEC-Q200-R	85±2℃. )±12hrs. room temperature after o 3hrs
9	Thermal shock test	Electric specifications should be satisfied	Step2:Room t 0.2 min. Step3:+125+2 Number of cy	$1-2^{\circ}C$ 15±1 min. temperature within ≤ 2 / -0°C 15±1min. cles:300 room temperature after o 3 hrs.
			Amplitude: Pa from any secu Directions and directions for This cycle sha times in each mutually perp (Total 12hour	d times: X, Y, Z 20 min. all be performed 12 of three endicular directions
11	Reflow test		Pre-heat: 15 Duration: 5 n Temperature: seconds	
	Solder test	Terminals should be covered by over 95% solder on visual inspection	235±5℃,4± Flux 、solder	
			DWG.No.	ASDIQ-SPE-149(00)
				1

#### (8)Soldering and Mounting 8-1,Soldering

Mildly activated rosin fluxes are preferred. ASDI terminations are suitable for all wave and reflow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

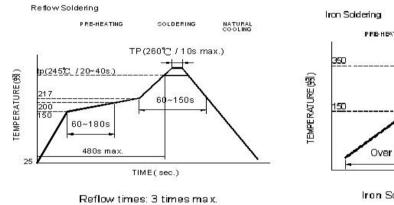
8-3,Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

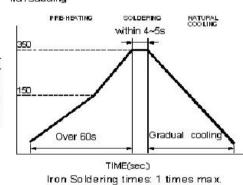
## 8-4, Soldering Iron

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

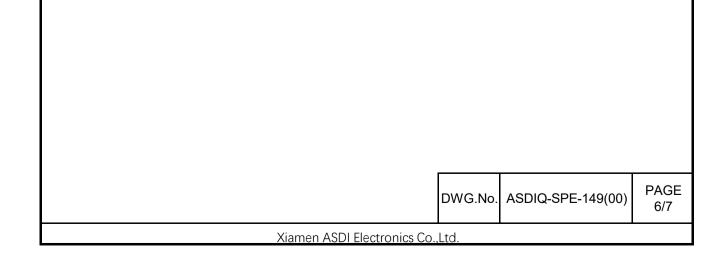
- ·Preheat circuit and products to 150  $^\circ\!\!\!\mathrm{C}$
- $\cdot \ensuremath{\mathsf{Never}}$  contact the ceramic with the iron tip
- ·Use a 20 watt soldering iron with tip diameter of 1.0mm
- $\cdot 355^{\circ}$ C tip temperature (max)
- ·1.0mm tip diameter (max)





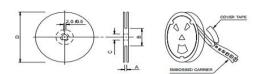






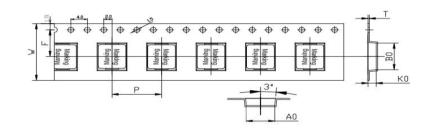
#### (9)Packaging Information

9-1,Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
13"x12mm	12.0±0.5	100±2	13.5±0.5	330.0

9-2, Tape Dimension

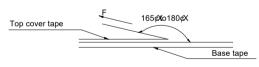


Туре	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)
SIPM0502	6.2±0.1	5.6±0.1	2.1±0.1	8.0±0.1	12±0.3	5.5±0.1	0.35±0.05

#### 9-3, Packaging Quantity

Chip size	502
Chip / Reel	2000

#### 9-4, Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in	
the arrow direction under the following conditions.	

Room Temp.	Room Humidity	Room atm	Tearing Speed	
(°C)	(%)	(hPa)	mm/min	
5~35	45~85	860~1060	300	

#### (10)Note

- •Storage Conditions To maintain the solderability of terminal electrodes: 1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Temperature: 5 to 30deg.C, Humidity: 75% Max.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- ·Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

The use of tweezers or vacuum pick up is strongly recommended for individual components.
Bulk handling should ensure that abrasion and mechanical shock are minimized.

	DWG.No.	ASDIQ-SPE-149(00)	PAGE 7/7
Xiamen ASDI Electronics Co.,Ltd.			•